

	Search Text	DBs
6	("5432303" "5434363" "5436471" "5438751" "5439554" "5440149" "5444188" "5446245" "5449940" "5460886" "5462891" "5464714" "5464950" "5471095" "5476815" "5478699" "5480841" "5485192" "5491505" "5496432" "5497020" "5512381" "5517050" "5517341" "5517342" "5521413" "5521421" "5521731" "5523253" "5523626" "5528403" "5528826"	USPAT
7	((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.	USPAT
8	(((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and mottle	USPAT
9	(((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and adhesion	USPAT

	Search Text	DBs
10	((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and (via or vias or hole or holes or opening or openings)	USPAT
11	(((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and adhesion) and (((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and (via or vias or hole or holes or opening or openings)))	USPAT
12	((((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and adhesion) and ((((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and (via or vias or hole or holes or opening or openings)))) and (adhesion adj promotion or adhesion adj promoting or adhesion adj strength or adhesive strength)	USPAT
13	((((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and adhesion) and ((((((174/255) or (174/262) or (174/261) or (174/264) or (174/256) or (361/792) or (361/803) or (428/209)).CCLS.) and (via or vias or hole or holes or opening or openings)))) and (conductive adj paste)	USPAT
14	(board or substrate) with (via or vias or hole or holes or opening or openings) with (mottle) with (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
15	(board or substrate) with (via or vias or hole or holes or opening or openings) with (adhesion adj promotion or adhesion adj promoting or adhesion adj strength or adhesive strength) with (conductive adj powder\$1 or conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
16	("4139881"   "4383363"   "4991060"   "5200579"   "5283104"   "5326636"   "5346750"   "5481795"   "5698015"   "5714238"   "5855820"   "6096411"   "6139777").PN.	USPAT
17	(board or substrate) same (via or vias or hole or holes or opening or openings) same (mottle) same (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
18	(board or substrate) and (via or vias or hole or holes or opening or openings) and (mottle) and (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
19	(board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion adj promotion or adhesion adj promoting or adhesion adj strength or adhesive strength) and (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
20	((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion adj promotion or adhesion adj promoting or adhesion adj strength or adhesive strength) and (conductive adj powder\$1 or conductive adj particle\$1)) and (zink adj layer or nickle adj layer or zink adj coating or nickel coating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
21	((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion adj promotion or adhesion adj promoting or adhesion adj strength or adhesive strength) and (conductive adj powder\$1 or conductive adj particle\$1)) and agglutination	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
22	((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion adj promotion or adhesion adj promoting or adhesion adj strength or adhesive strength) and (conductive adj powder\$1 or conductive adj particle\$1)) and (zink adj layer or nickle adj layer or zink adj coating or nickel coating)) and (chromate or silane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
23	(174/262).CCLS.	USPAT

	Search Text	DBs
24	("3934335"   "RE29784"   "4303715"   "4854038"   "4894271"   "4911796"   "5055342"   "5137461"   "5208068"   "5285017"   "5374788"   "5386088"   "5559369"   "5709957"   "5879787"   "5930668"   "6120639"   "6175087"   "6201194"   "6204453"   "6333466"   "6335076").PN.	USPAT
25	(174/255).CCLS.	USPAT
26	((174/255).CCLS.) not ((174/262).CCLS.)	USPAT
27	(174/261).CCLS.	USPAT
28	((174/261).CCLS.) not ((174/255).CCLS.)	USPAT
29	(((174/261).CCLS.) not ((174/255).CCLS.)) not ((174/262).CCLS.)	USPAT
30	((174/264) or (174/256)).CCLS.	USPAT
31	(((174/264) or (174/256)).CCLS.) not ((174/261).CCLS.)	USPAT
32	((((174/264) or (174/256)).CCLS.) not ((174/261).CCLS.)) not ((174/255).CCLS.)	USPAT
33	((((((174/264) or (174/256)).CCLS.) not ((174/261).CCLS.)) not ((174/255).CCLS.)) not ((174/262).CCLS.))	USPAT
34	(board or substrate) with (via or vias or hole or holes or opening or openings) with (protective adj agent or protective adj layer) with (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
35	(board or substrate) same (via or vias or hole or holes or opening or openings) same (protective adj agent or protective adj layer) same (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
36	(board or substrate) and (via or vias or hole or holes or opening or openings) and (protective adj agent or protective adj layer) and (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
37	((board or substrate) and (via or vias or hole or holes or opening or openings) and (protective adj agent or protective adj layer) and (conductive adj powder\$1 or conductive adj particle\$1)) not (((174/264) or (174/256)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
38	(((board or substrate) and (via or vias or hole or holes or opening or openings) and (protective adj agent or protective adj layer) and (conductive adj powder\$1 or conductive adj particle\$1)) not (((174/264) or (174/256)).CCLS.)) not ((174/261).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
39	(((board or substrate) and (via or vias or hole or holes or opening or openings) and (protective adj agent or protective adj layer) and (conductive adj powder\$1 or conductive adj particle\$1)) not (((174/264) or (174/256)).CCLS.)) not ((174/261).CCLS.)) not ((174/255).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
40	((((board or substrate) and (via or vias or hole or holes or opening or openings) and (protective adj agent or protective adj layer) and (conductive adj powder\$1 or conductive adj particle\$1)) not (((174/264) or (174/256)).CCLS.)) not ((174/261).CCLS.)) not ((174/255).CCLS.)) not ((174/262).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
41	(board or substrate) with (via or vias or hole or holes or opening or openings) with (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) with (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
42	(board or substrate) same (via or vias or hole or holes or opening or openings) same (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) same (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
43	((board or substrate) same (via or vias or hole or holes or opening or openings) same (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) same (conductive adj powder\$1 or conductive adj particle\$1)) not US-6488869-B2.DID.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
44	((board or substrate) same (via or vias or hole or holes or opening or openings) same (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) same (conductive adj powder\$1 or conductive adj particle\$1)) not ((board or substrate) with (via or vias or hole or holes or opening or openings) with (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) with (conductive adj powder\$1 or conductive adj particle\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
45	(board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) and (conductive adj powder\$1 or conductive adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
46	((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) and (conductive adj powder\$1 or conductive adj particle\$1)) and (zink or nickel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
47	((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) and (conductive adj powder\$1 or conductive adj particle\$1)) and (chromate or silane)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
48	((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) and (conductive adj powder\$1 or conductive adj particle\$1)) and (zink or nickel)) or ((board or substrate) and (via or vias or hole or holes or opening or openings) and (adhesion near3 promotion or adhesion near3 promoting or adhesion near3 strength or adhesive near3 strength or protective near3 agent) and (conductive adj powder\$1 or conductive adj particle\$1)) and (chromate or silane))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
49	(US-6534723-\$ or US-6488869-\$ or US-6459047-\$ or US-5481795-\$ or US-5346750-\$ or US-5029242-\$ or US-4967314-\$ or US-6096411-\$ or US-6574114-\$ or US-6362090-\$ or US-6190737-\$ or US-6149857-\$ or US-6139777-\$ or US-6111684-\$ or US-5851644-\$ or US-5830613-\$ or US-5607802-\$ or US-5571649-\$ or US-5549990-\$ or US-5437950-\$ or US-5415893-\$ or US-5378566-\$ or US-5001302-\$).did.	USPAT
50	((US-6534723-\$ or US-6488869-\$ or US-6459047-\$ or US-5481795-\$ or US-5346750-\$ or US-5029242-\$ or US-4967314-\$ or US-6096411-\$ or US-6574114-\$ or US-6362090-\$ or US-6190737-\$ or US-6149857-\$ or US-6139777-\$ or US-6111684-\$ or US-5851644-\$ or US-5830613-\$ or US-5607802-\$ or US-5571649-\$ or US-5549990-\$ or US-5437950-\$ or US-5415893-\$ or US-5378566-\$ or US-5001302-\$).did.) and ((porous or non adj continuous) with (nickel or silane or chromate or zinc))	USPAT
51	(surface adj treatment or surface adj preparation) with (porous or non adj continuous) with (nickel or silane or chromate or zinc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB

	Search Text	DBs
52	(surface adj treatment or surface adj preparation) with (porous or non adj continuous) with (nickel or silane or chromate or zinc) with (copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
53	(surface adj treatment or surface adj preparation or surface adj coating) with (copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
54	((surface adj treatment or surface adj preparation or surface adj coating) with (copper)) and ((porous or non adj continuous) with (nickel or silane or chromate or zinc))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
55	(surface adj treatment or surface adj preparation or surface adj coating) with (copper adj foil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
56	mottle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
57	((surface adj treatment or surface adj preparation or surface adj coating) with (copper adj foil)) and mottle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
58	((surface adj treatment or surface adj preparation or surface adj coating) with (copper)) and mottle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
59	mottle and (board or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
60	(mottle and (board or substrate)) and (copper adj foil)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
61	(mottle and (board or substrate)) and (surface adj treatment or surface adj preparation or surface adj coating)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
62	(copper adj foil) with (protection or protective)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB



	Search Text	DBs
63	"428" and (porous or non adj continuous) and (nickel or silane or chromate or zinc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
64	((copper adj foil) with (protection or protective)) and (porous or non adj continuous) and (nickel or silane or chromate or zinc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB
65	("3886022"   "3936548"   "3990926"   "3998601"   "4088544"   "4293617"   "4357395"   "5057372"   "5617629").PN.	USPAT
66	6183880.URPN.	USPAT